

RADIATION SHIELDING OF INTEGRATED CIRCUITS AND MULTI-CHIP MODULES IN CERAMIC AND METAL PACKAGES

ABSTRACT

A radiation shielded and packaged integrated circuit semiconductor device includes a lid secured to a base to enclose an integrated circuit die within, wherein the lid and the base are each constructed from a high Z material to prevent radiation from penetrating therethrough. Another embodiment includes a die attach slug constructed from a high Z material disposed between the integrated circuit die and the base, in combination with a high Z material lid to substantially block incident radiation.